

**IEC SYSTEM FOR MUTUAL RECOGNITION OF TEST CERTIFICATES FOR ELECTRICAL EQUIPMENT (IECEE)
CB SCHEME**

CB TEST CERTIFICATE

Product

1) Intel® NUC Rugged Chassis Element (Docking)
2) Intel® NUC Pro Chassis Element (Docking)

Name and address of the applicant

INTEL CORPORATION
2200 MISSION COLLEGE BLVD SANTA CLARA, CA
95054-1537 USA

Name and address of the manufacturer

INTEL CORPORATION
2200 MISSION COLLEGE BLVD SANTA CLARA, CA
95054-1537 USA

Name and address of the factory

GOLDEN ELITE TECHNOLOGY (SHEN ZHEN) LTD
1 NAN HUAN RD SHAJING BAO AN SHENZHEN GUANGDONG
518104
CHINA

Note: When more than one factory, please report on page 2

Additional Information on page 2

Ratings and principal characteristics

19 Vdc., 4.74 A

Trademark / Brand (if any)



Type of Customer's Testing Facility (CTF) Stage used

Model / Type Ref.

1) xCMCR1ABx, 2) xCMCM2FBx
(where x can be a combination of alphanumeric characters,
none or blank)

Additional information (if necessary may also be reported on page 2)

Additional Information on page 2

A sample of the product was tested and found to be in conformity with

IEC 62368-1:2014

As shown in the Test Report Ref. No. which forms part of this Certificate

ATTCB108120-02 issued on 2020-07-08

This CB Test Certificate is issued by the National Certification Body



- UL (US), 333 Pfingsten Rd IL 60062, Northbrook, USA
- UL (Demko), Borupvang 5A DK-2750 Ballerup, DENMARK
- UL (JP), Marunouchi Trust Tower Main Building 6F, 1-8-3 Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN
- UL (CA), 7 Underwriters Road, Toronto, M1R 3B4 Ontario, CANADA

For full legal entity names see www.ul.com/ncbnames

Date: 2020-07-10
Original Issue Date: 2019-10-18

Signature:

Jan-Erik Storgaard



Ref. Certif. No.

DK-88652-A1-UL

Additional Information:

Additionally evaluated to EN 62368-1:2014/A11:2017

National Difference specified in the CB Test Report

Reason for Correction:

-Correct amendment information due to typo, see below for details:

Add new construction for new model name: xCMCM2FBx with xCM8xCBx (type A, type B, type C) and xCMB1ABx (type B) as below:

- Add product name: Intel® NUC Pro Chassis Element (Docking)
- Add thermal pad (type D)
- Add ambient (35 °C)
- Add enclosure chassis (type B)
- Add heatsink (type B) with DC Fan.
- Add VESA mount (type B) (optional)
- Add daughter board (optional)

Additional information (if necessary)



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